

Data Sheet

July 1999

File Number

2881.2

2A, 200V, 3.500 Ohm, N-Channel Power MOSFET

These are N-Channel enhancement mode silicon gate power field effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

Formerly developmental type TA09289.

Ordering Information

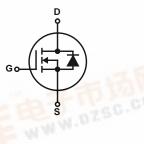
PART NUMBER	PACKAGE	BRAND
RFP2N20	TO-220AB	RFP2N20

NOTE: When ordering, include the entire part number.

Features

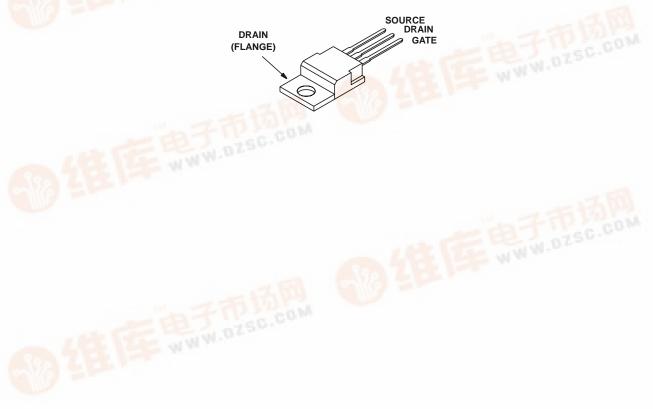
- 2A, 200V
- $r_{DS(ON)} = 3.500\Omega$

Symbol



Packaging

JEDEC TO-220AB





RFP2N20

Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified

	RFP2N20	UNITS
Drain to Source Voltage (Note 1)	200	V
Drain to Gate Voltage (RGS = $20k\Omega$) (Note 1)	200	V
Continuous Drain Current	2	Α
Pulsed Drain Current (Note 3)	5	Α
Gate to Source Voltage	±20	V
Maximum Power Dissipation	25	W
Linear Derating Factor	0.2	W/ °C
Operating and Storage Temperature	-55 to 150	°C
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s	300 260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}C$ to $125^{\circ}C$.

$\textbf{Electrical Specifications} \hspace{0.5cm} \textbf{T}_{C} = 25^{o}\text{C, Unless Otherwise Specified}$

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0	200	-	-	
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 250\mu$ A, (Figure 8)	2	-	4	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = Rated BV _{DSS}	-	-	1	μΑ
		V _{DS} = 0.8 x Rated BV _{DSS} , T _C = 125°C	-	-	25	μА
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0$	-	-	±100	nA
Drain to Source On Resistance (Note 2)	r _{DS(ON)}	I _D = 2A, V _{GS} = 10V, (Figures 6, 7)	-	-	3.500	Ω
Drain to Source On Voltage (Note 2)	V _{DS(ON)}	I _D = 2A, V _{GS} = 10V	-	-	7.0	V
Turn-On Delay Time	t _{d(ON)}	$I_D \approx$ 1A, V_{DD} = 100V, R_G = 50Ω V_{GS} = 10V, R_L = 96.5Ω (Figure 10)	-	15	25	ns
Rise Time	t _r		-	20	30	ns
Turn-Off Delay Time	t _{d(OFF)}		-	25	40	ns
Fall Time	t _f		-	15	25	ns
Input Capacitance	C _{ISS}	V _{GS} = 0V, V _{DS} = 25V f = 1MHz, (Figure 9)	-	-	200	pF
Output Capacitance	C _{OSS}		-	-	60	pF
Reverse-Transfer Capacitance	C _{RSS}		-	-	25	pF
Thermal Resistance Junction to Case	$R_{ heta JC}$		-	-	5	oC/W

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V _{SD}	I _{SD} = 1A	-	-	1.4	V
Diode Reverse Recovery Time	t _{rr}	$I_{SD} = 2A$, $dI_{SD}/dt = 50A/\mu s$	-	200	-	ns

NOTES:

- 2. Pulsed test: width $\leq 300\mu s$ duty cycle $\leq 2\%$.
- 3. Repetitive rating: pulse width limited by maximum junction temperature.

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Typical Performance Curves Unless Otherwise Specified

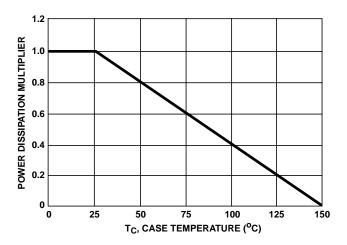


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

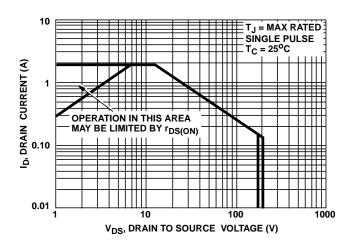


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

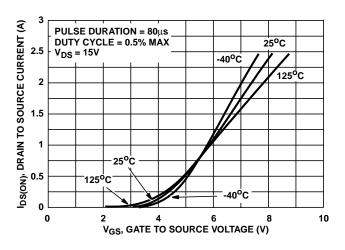


FIGURE 5. TRANSFER CHARACTERISTICS

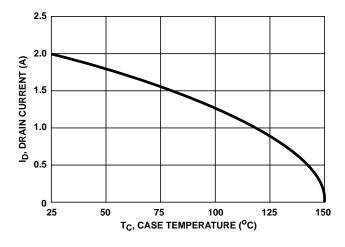


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

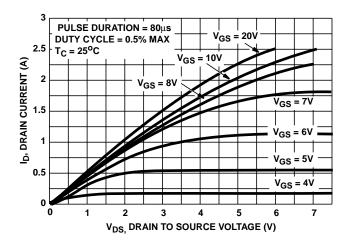


FIGURE 4. SATURATION CHARACTERISTICS

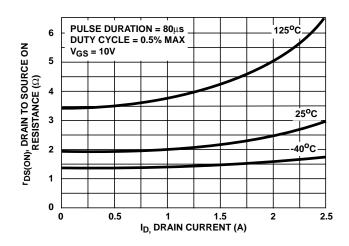


FIGURE 6. DRAIN TO SOURCE ON RESISTANCE VS DRAIN CURRENT

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Typical Performance Curves Unless Otherwise Specified (Continued)

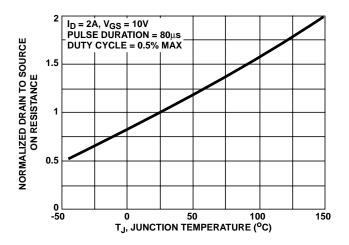


FIGURE 7. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

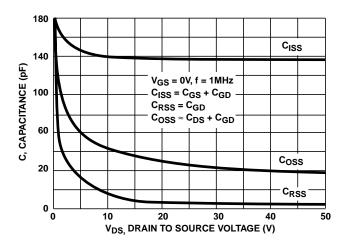


FIGURE 9. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

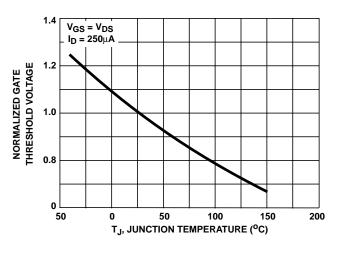
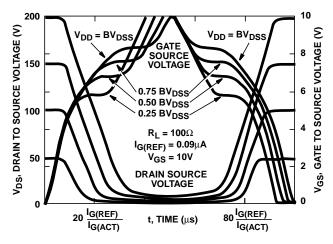


FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE



NOTE: Refer to Intersil Applications Notes AN7254 and AN7260

FIGURE 10. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

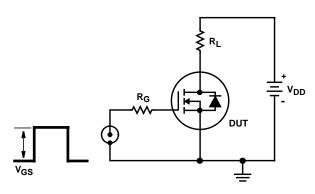


FIGURE 11. SWITCHING TIME TEST CIRCUIT

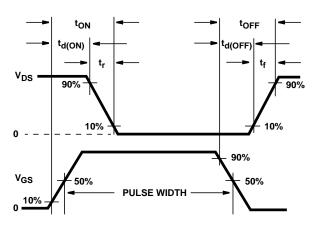


FIGURE 12. RESISTIVE SWITCHING WAVEFORMS

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RFP2N20

Test Circuits and Waveforms

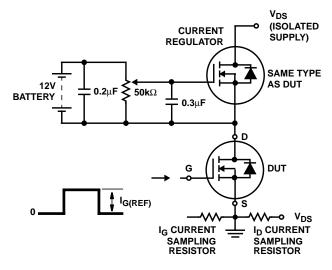


FIGURE 13. GATE CHARGE TEST CIRCUIT

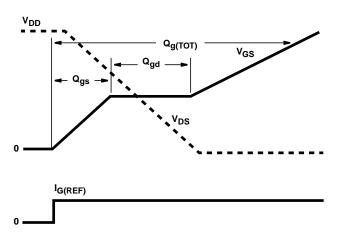


FIGURE 14. GATE CHARGE WAVEFORMS

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